

ALPHA[®] WS-820

Water Soluble, Lead-Free Solder Paste

DESCRIPTION

ALPHA WS-820 a lead free, halide free solder paste offering the ideal combination of printability and reflow profile process window, with excellent cleanability in a lead-free alloy solder paste.

FEATURES & BENEFITS

- Excellent print volume and print volume repeatability down to 12 mil (0.3mm) features
- Able to spread and wet using straight ramp or soak reflow profiles in air
- High spread/wetting lead free paste compatible with lead free alloys and surface finishes
- High Reflow Yield with IPC Class II Voiding Performance when used to solder BGA components
- Excellent wetting characteristics on all common surface finishes (including ENTEK HT OSP). JIS Spread 88.6% on ENTEK HT OSP
- Cleanable with water-based cleaning systems

PRODUCT INFORMATION

<u>Alloys:</u>	SAC305, SAC405, SACX [®] Plus 0807, 96.5Sn3.5Ag, 95.5Sn3.8Ag0.7Cu, 95.5Sn4Ag0.5Cu & Innolot
<u>Powder Size:</u>	Type 3 & Type 4
<u>RoHS Status:</u>	Completely free of Hazardous Materials per RoHS Directive 2002/95/EC

APPLICATION GUIDELINES

ALPHA WS-820 was formulated to meet the requirements of water soluble solder lead free applications. ALPHA WS-820 was developed to increase the reflow profile window of WS-819, while offering exceptional post reflow cleanability and low BGA voiding.

This paste is designed to enable users of ALPHA WS-609, WS-709 and WS-809 and other leading water soluble paste brands to comply with RoHS and customer based demand for lead free materials.

TECHNICAL DATA

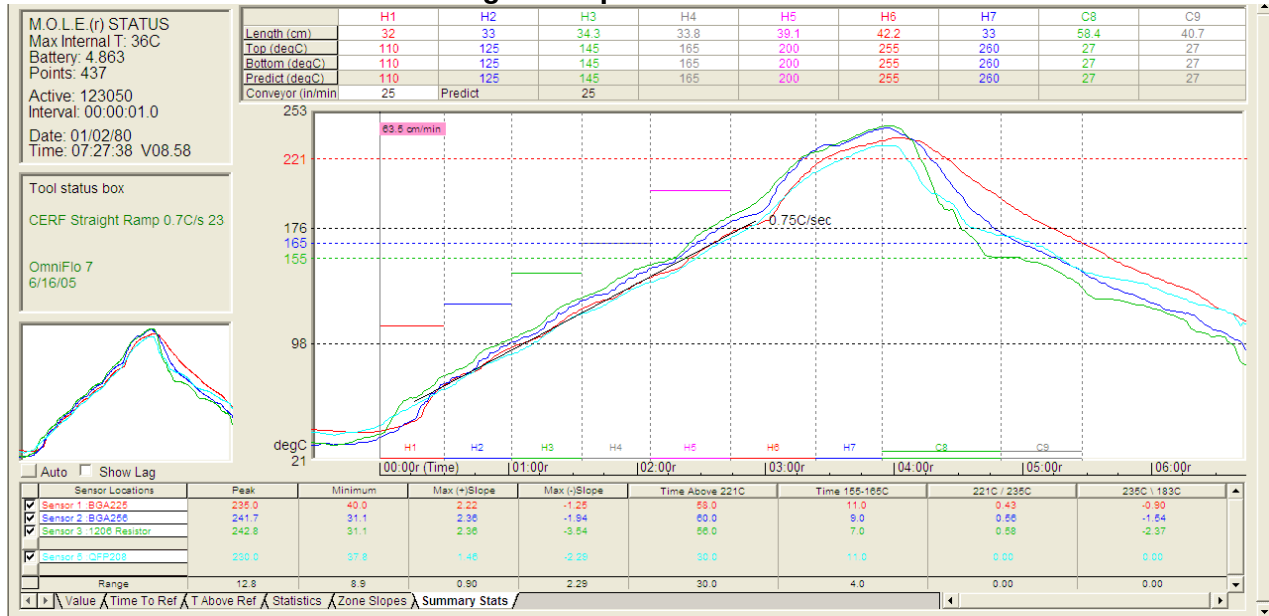
Category	Results	Procedures/ Remarks
Physical Properties		
Appearance (flux residues after reflowed)	Light yellowish color (before water washed)	
Stencil life Capable of printing in temperatures from 20 to 28 °C (50% +/-15%RH, @25 °C)	8 hours	ALPHA-GLB-PUT-0012
Printability	Suitable for fine pitch printing applications (Down to 16 mil (0.4mm) pitch QFP components, 12 mil (0.3mm) BGA circles @) up to 100 mm/sec squeegee speed, using 5 mil (125µ) thick laser cut stencil	ALPHA-GLB-PUT-0001
Response to pause	0 to 1 Knead Stroke Required	ALPHA-GLB-PUT-0008
Tack	Initial 2.0 g/mm ² ; 1.8 g/mm ² after 4 hours at 25 °C and 50% R.H.	IPC TM-650 2.4.44
Random Solder Balls	Preferred (Both Initial & after 4 hours at 25 °C and 50% R.H.)	ALPHA-GLB-PUT-0005
Slump Resistance	Pass	IPC TM-650 2.4.35
Chemical Properties		
Items ALPHA WS-820 Flux System		
Halide content (IPC J-Std-004)	ORH0	
Corrosivity (IPC J-Std-004)	Not applicable for water soluble solder paste	

PROCESSING GUIDELINES

Storage-Handling	Printing / Dispensing	Reflow	Cleaning
• Refrigerate to guarantee stability @ 32 to 50 °F (0 to 10 °C). Expected shelf life is 6 months from date of manufacture in unopened jars. • Warm-up of 500g jar to room temperature (should be ~ 6 hours). Set up printer with room temperature paste. Check paste temperature with a thermometer. • Do not remove worked paste from stencil and mix with unused paste in jar. This will alter rheology of unused paste. • Do not shake or mix paste using automatic paste shaking equipment prior to opening jar. The plunger insert used may submerge into paste and produce difficulties with plunger removal. • Paste is stable for up to two weeks at room temperature (25 °C).	Stencil: Recommend ALPHA CUT Laser Cut Stencil @ 0.005 inch (5 mil, 127μ) thick for 0.012 inch (.30 mm) pitch QFPs Squeegee: Metal (Recommended) Print Speed: 2.0 to 4.0 in./sec (50 to 100 mm/sec.) 4.0 in/sec. optimal Pressure: 1.5 to 2.0 lbs./ linear in. (0.268 to 0.357 Kg/cm) Stencil Release Speed: .02 in/sec (0.5 mm/second)	Atmosphere: • Clean-dry air or Nitrogen Profile (Printing): • See profiles evaluated in product development below • If there is a significant ΔT (>10 °C) between components, a soak profile may be required. (Slow ramp from 130 °C to 180 °C for 60 to 90 seconds) • Ramp @ 0.5 to 2 °C/sec to peak temperature 230 to 250 °C TAL for 40 to 80 seconds. • Ramp down to R.T. @ 1 to 3 °C/sec.	• ALPHA WS-820 is designed to be water rinsed in washing operations. With minimal foaming in recirculating systems. • The flux residues from ALPHA WS-820 are completely water soluble. This allows for more flexible washing conditions which can be board design specific. • Effective residue cleanability up to 48 hours after reflow. This allows maximum process flexibility. • If lower/no foaming is desired in cleaning equipment, Alpha 2002D defoamer may be used. • Cleaning temperature of 150 °F (65 °C) may cause the undesirable formation of tin salts.

REFLOW PROFILES

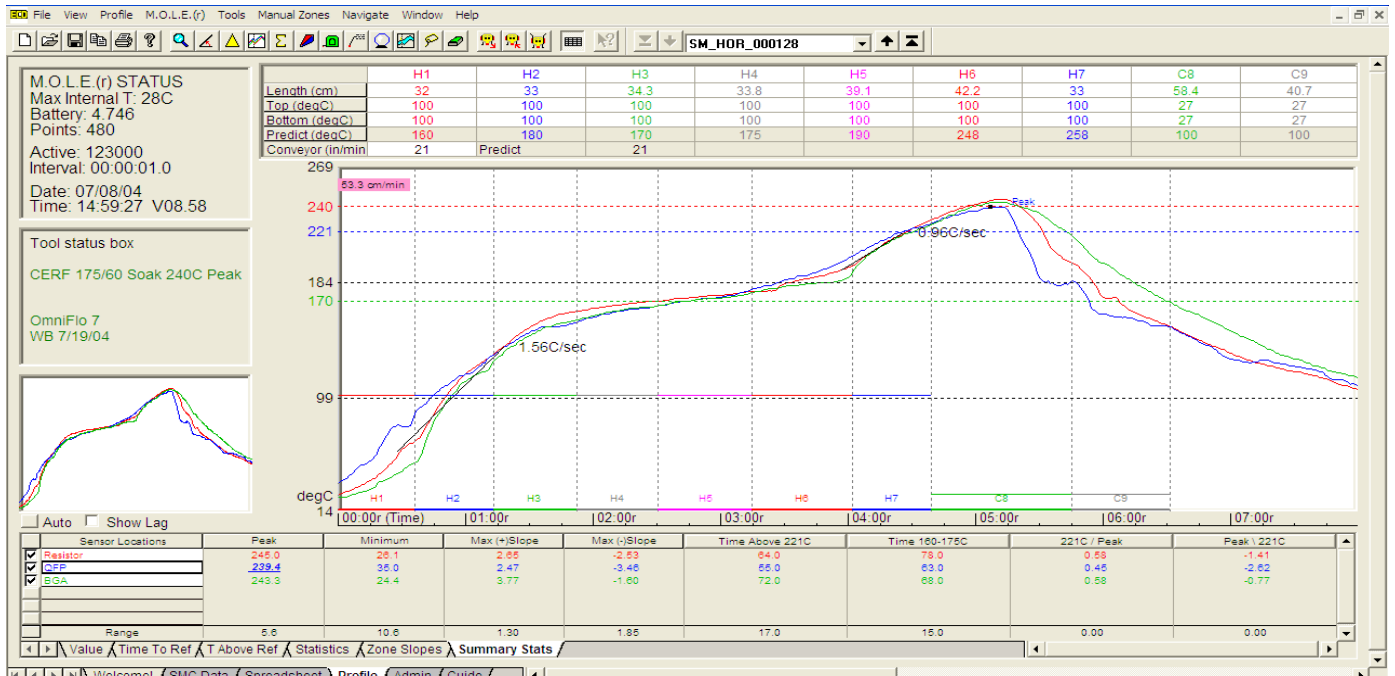
Reflow Profiles Tested, using Clean, Dry Air /
CERF Straight Ramp 0.7C/s 235C Peak 60s TAL



CERF Straight Ramp 1.5C/s 240C Peak 60s TAL



CERF 60s Soak @ 175°C/ 240C Peak 60s TAL



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at AlphaAssembly.com**

STORAGE

ALPHA WS-820 is shipped in thermally controlled boxes and should be stored refrigerated upon receipt at 32 to 50 °F (0 to 10 °C). ALPHA WS-820 should be permitted to reach room temperature before opening the package prior to use. When stored properly in unopened containers, ALPHA WS-820 has a shelf life of 6 months from date of manufacture.

CONTACT INFORMATION

**To confirm this document is the most recent version, please contact
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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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